IPC ASSOCIATION CONNE	Material Compo © Copyright 2005. II international and Pan	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard  Form Type http://www.ipc.org/IPC-175x  Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfc Information			
upplier Info									,						
Company name* Company unique ID					Ţ	Unique ID Authority					Response Date*				
nsemi										2024-05-21					
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Ste	ewards		Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com					
uthorized Repr	resentative*	Title - Repres	Title - Representative			Phone - Representative*			Email - Representative*						
Product-Env-Ste	ewards		Product Envi	ro Compliance			NA Pro					Product-Env-Stewards@onsemi.com			
Reque	Requester Item Number Mfr Iter		Number Mfr Item Name			Effective Date	Version	n ]	Manufacturing Site	1	Weight*	UOM	Unit Type		
		AR0220A A2-DPB	AT4B00XUE R	2MP 1/2 CIS SO			2024-05-21		,	TWU	2	299.38	mg	Each	
<b>Ianufacturi</b> r	ng Proccess Informat	tion													
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL				L Rating	Peak Proc	ess Body	Temperatu	re Max Time at Peak	Temperat	ure Numb	er of Reflow Cyc	cles			
SnAgCu		CU Alloy	3	3		260		С	30	secon	ds 3				
omments															
ΓΤΕΝΤΙΟΝ: M	ASL 3 Rated item requires	s Bake and D	ry Pack (after	electrical test)											
or more inform	ation regarding material	composition	please refer to	page 3						·			·	·	

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	62.98	mg		Misc.	proprietary data		0.2393	mg
			Supplier	Silicon (Si)	7440-21-3		62.1172	mg
			Supplier	Aluminum (Al)	7429-90-5		0.6235	mg
Die Attach	3.84	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		1.44	mg
			Supplier	Ethylene Glycol	107-21-1		0.0384	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.1152	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.8064	mg
			Supplier	Formaldehyde Polymer	9003-36-5		1.44	mg
Imaging Lens	56.08	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.804	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		2.804	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		2.804	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		2.804	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2804	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.804	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		2.804	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		38.9756	mg
Lid Attach	1.83	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.183	mg
			Supplier	Filler (SiO2)	68909-20-6		0.183	mg
			Supplier	Other Additive Agents	Proprietary Data		0.183	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.549	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.732	mg
Mold Compound-Black	72.8	mg		Phenolic Resin	proprietary data		10.92	mg
			Supplier	Oxirane	39817-09-9		10.92	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		2.184	mg
			Supplier	Carbon Black (C)	1333-86-4		0.728	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		46.592	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.456	mg
Solder Ball	49.53	mg	Supplier	Silver (Ag)	7440-22-4		1.4859	mg
			Supplier	Tin (Sn)	7440-31-5		47.7964	mg
			Supplier	Copper (Cu)	7440-50-8		0.2476	mg
Substrate and Solder Mask	52.0	mg	Supplier	Acetophenone	98-86-2		1.0192	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		11.5388	mg

			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6	0.6812	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	0.6864	mg
			Supplier	Carbon Black (C)	1333-86-4	0.1716	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.1716	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	2.0384	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	5.2	mg
			Supplier	Copper (Cu)	7440-50-8	25.22	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	5.2728	mg
Wire Bond - Au	0.32	mg	Supplier	Gold (Au)	7440-57-5	0.32	mg